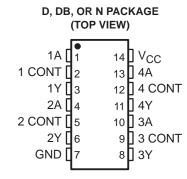
SN75C189, SN75C189A QUADRUPLE LOW-POWER LINE RECEIVERS

SLLS041G - OCTOBER 1988 - REVISED JANUARY 2000

- Meet or Exceed the Requirements of TIA/EIA-232-F and ITU Recommendation V.28
- Low Supply Current . . . 420 μA Typ
- Preset On-Chip Input Noise Filter
- Built-in Input Hysteresis
- Response and Threshold Control Inputs
- Push-Pull Outputs
- Functionally Interchangeable and Pin-to-Pin Compatible With Texas Instruments SN75189/SN75189A and Motorola MC1489/MC1489A
- Package Options Include Plastic Small-Outline (D) and Shrink Small-Outline (DB) Packages, and Standard Plastic (N) DIP



description

The SN75C189 and SN75C189A are low-power, bipolar, quadruple line receivers that are used to interface data terminal equipment (DTE) with data circuit-terminating equipment (DCE). These devices have been designed to conform to TIA/EIA-232-F.

The SN75C189 has a 0.33-V typical hysteresis, compared with 0.97 V for the SN75C189A. Each receiver has provision for adjustment of the overall input threshold levels. This is achieved by choosing external series resistors and voltages to provide bias levels for the response-control pins. The output is in the high logic state if the input is open circuit or shorted to ground.

These devices have an on-chip filter that rejects input pulses of less than 1-µs duration. An external capacitor can be connected from the control pins to ground to provide further input noise filtering for each receiver.

The SN75C189 and SN75C189A have been designed using low-power techniques in a bipolar technology. In most applications, these receivers interface to single inputs of peripheral devices such as UARTs, ACEs, or microprocessors. By using sampling, such peripheral devices usually are insensitive to the transition times of the input signals. If this is not the case, or for other uses, it is recommended that the SN75C189 and SN75C189A outputs be buffered by single Schmitt input gates or single gates of the HCMOS, ALS, or 74F logic families.

The SN75C189 and SN75C189A are characterized for operation from 0°C to 70°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

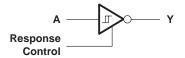


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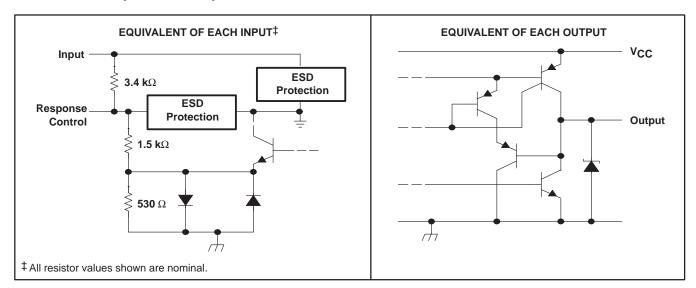
logic symbol†

╜ **THRESHOLD** 1 CONT **ADJUST** 4 6 2 CONT 10 **3A** 3 CONT 13 12 4 CONT

logic diagram (each receiver)



schematic of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)§

Supply voltage, V _{CC} (see Note 1)		7 V
Input voltage range, V ₁		
Output voltage range, VO		\dots -0.3 V to V _{CC} + 0.3 V
Package thermal impedance, θ _{JA} (see Note 2): D package	86°C/W
	DB package	96°C/W
	N package	
Lead temperature 1,6 mm (1/16 inch) from cas	se for 10 seconds	260°C
Storage temperature range, T _{stg}		–65°C to 150°C

[§] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to network GND.

2. The package thermal impedance is calculated in accordance with JESD 51.



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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recommended operating conditions

		MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	6	V
VI	Input voltage (see Note 3)	-25		25	V
IOH	High-level output current			-3.2	mA
loL	Low-level output current			3.2	mA
	Response-control current			±1	mA
TA	Operating free-air temperature	0		70	°C

NOTE 3: The algebraic convention, where the more positive (less negative) limit is designated as maximum, is used in this data sheet for logic levels only, e.g., if –10 V is a maximum, the typical value is a more negative voltage.

electrical characteristics over recommended free-air temperature range, V_{CC} = 5 V \pm 10% (unless otherwise noted) (see Note 4)

	PARAMETER		TEST COND	MIN	TYP [†]	MAX	UNIT	
\/	Positive-going input threshold voltage	'C189	Soo Figure 1	1		1.5	V	
VIT+	Positive-going input threshold voltage	'C189A	See Figure 1		1.6		2.25	V
\/	Negative-going input threshold voltage	'C189	See Figure 1		0.75		1.25	V
VIT-	Negative-going input threshold voltage	'C189A	See Figure 1		0.75	1	1.25	V
\/,	V _{hys} Input hysteresis voltage (V _{IT+} – V _{IT-})		See Figure 1		0.15	0.33		V
v nys			See rigule r		0.65	0.97		V
\/a	Llink lavel autaut valtana		$V_{CC} = 4.5 \text{ V to 6 V},$ $I_{OH} = -20 \mu\text{A}$	$V_{I} = 0.75 V$,	3.5			V
VOH	VOH High-level output voltage		$V_{CC} = 4.5 \text{ V to 6 V},$ $I_{OH} = -3.2 \text{ mA}$	V _I = 0.75 V,	2.5			V
VOL	Low-level output voltage	$V_{CC} = 4.5 \text{ V to 6 V},$ $I_{OL} = 3.2 \text{ mA}$	V _I = 3 V,			0.4	>	
I	High-level input current		Soo Figure 2	V _I = 25 V	3.6		8.3	mA
l IH	riign-ieveriiiput current		See Figure 2 $V_1 = 3 \text{ V}$		0.43		1	IIIA
1	Low lovel input current		See Figure 2	V _I = -25 V	-3.6		-8.3	mA
Ŭ 'IL	I _L Low-level input current		See Figure 2	V _I = -3 V	-0.43		-1	IIIA
los	Short-circuit output current	See Figure 3				-35	mA	
Icc	Supply current	V _I = 5 V, See Figure 2	No load,		420	700	μА	

[†] All typical values are at $T_A = 25$ °C.

NOTE 4: All characteristics are measured with response-control terminal open.

switching characteristics, V_{CC} = 5 V $\pm 10\%$, T_A = 25°C

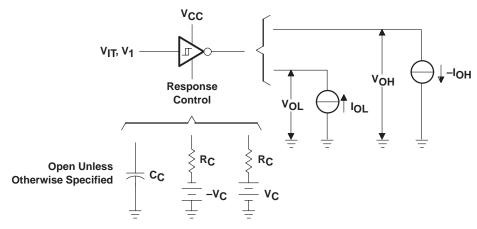
	PARAMETER	Т	EST CONDITIO	MIN	TYP	MAX	UNIT	
tPLH	Propagation delay time, low- to high-level output						6	μs
tPHL	Propagation delay time, high- to low-level output]					6	μs
tTLH	Transition time, low- to high-level output‡	$R_L = 5 \text{ k}\Omega$,	$C_{L} = 50 pF$,	See Figure 4			500	ns
tTHL	Transition time, high- to low-level output‡]					300	ns
t _{w(N)}	Duration of longest pulse rejected as noise§]			1		6	μs

[‡] Measured between 10% and 90% points of output waveform



[§] The receiver ignores any positive- or negative-going pulse that is less than the minimum value of $t_{W(N)}$ and accepts any positive- or negative-going pulse greater than the maximum of $t_{W(N)}$.

PARAMETER MEASUREMENT INFORMATION

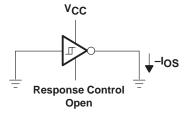


NOTE A: Arrows indicate actual direction of current flow. Current into a terminal is a positive value.

Figure 1. V_{T+} , V_{IT-} , V_{OH} , V_{OL}

NOTE A: Arrows indicate actual direction of current flow. Current into a terminal is a positive value.

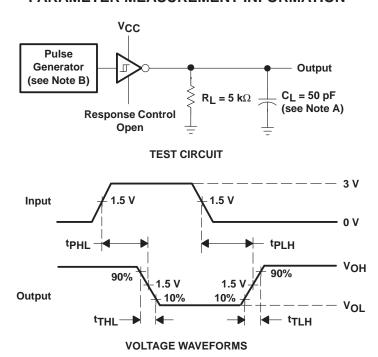
Figure 2. I_{IH}, I_{IL}, I_{CC}



NOTE A: Arrows indicate actual direction of current flow. Current into a terminal is a positive value.

Figure 3. Ios

PARAMETER MEASUREMENT INFORMATION

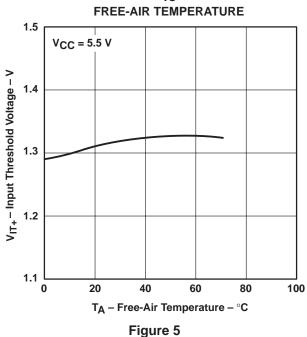


NOTES: A. C_L includes probe and jig capacitances.

B. The pulse generator has the following characteristics: Z $_{O}$ = 50 $\Omega,\,t_{W}$ = 25 $\mu s.$

Figure 4. Test Circuit and Voltage Waveforms

SN75C189 INPUT THRESHOLD VOLTAGE (POSITIVE GOING) vs



SN75C189A INPUT THRESHOLD VOLTAGE (POSITIVE GOING)

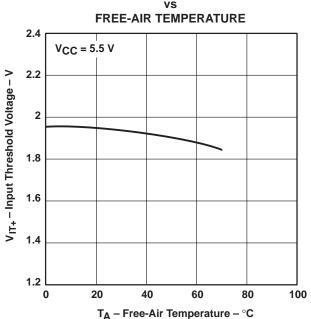
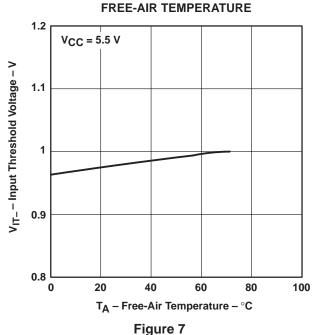
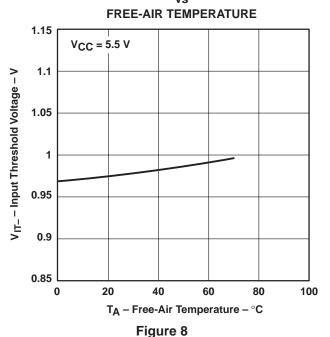


Figure 6

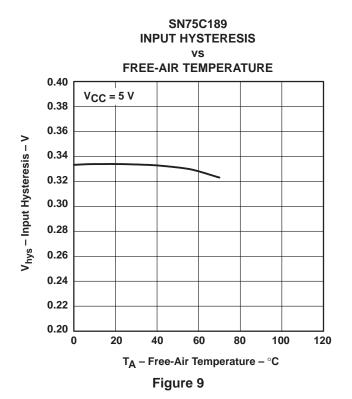
SN75C189 INPUT THRESHOLD VOLTAGE (NEGATIVE GOING) vs

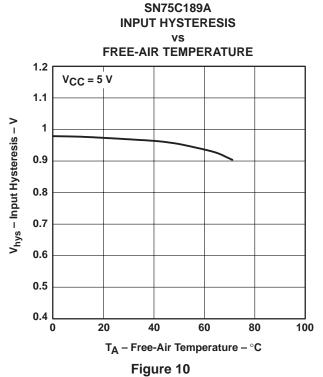


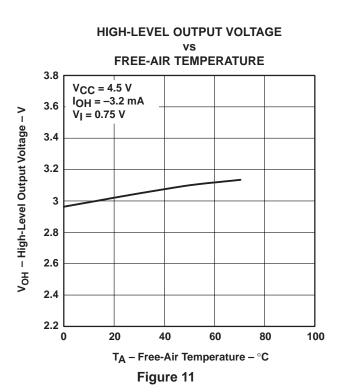
SN75C189A INPUT THRESHOLD VOLTAGE (NEGATIVE GOING) vs

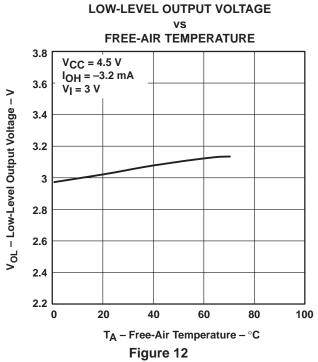


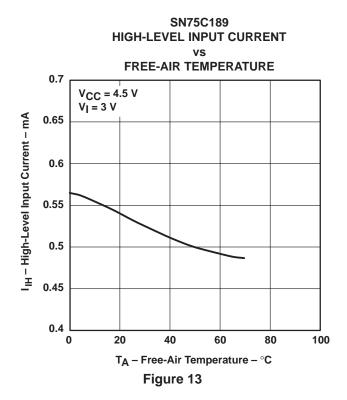


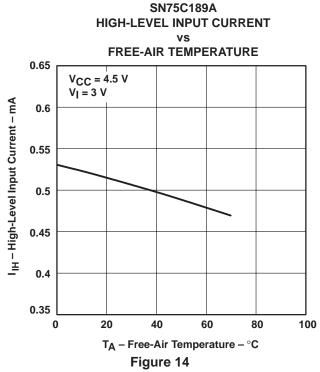


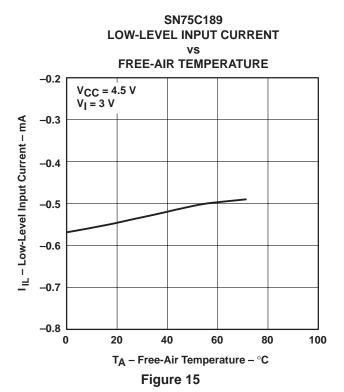


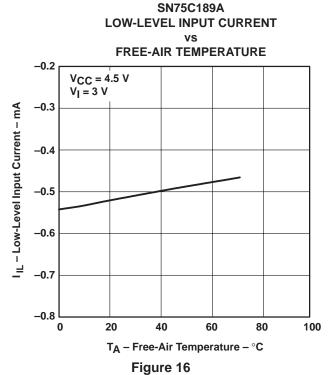












HIGH-LEVEL SHORT-CIRCUIT OUTPUT CURRENT

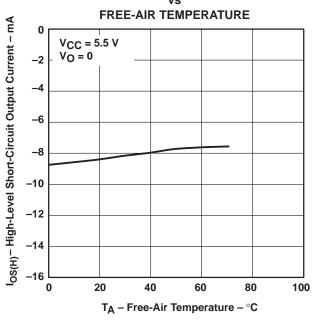


Figure 17

LOW-LEVEL SHORT-CIRCUIT OUTPUT CURRENT

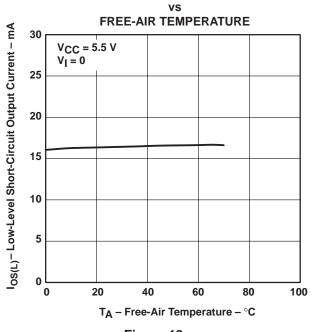


Figure 18

SUPPLY CURRENT vs

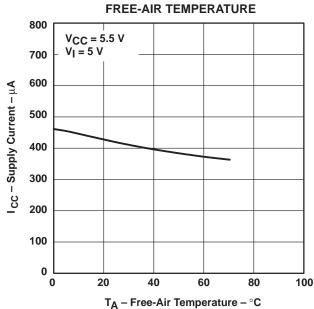


Figure 19

PROPAGATION DELAY TIME,

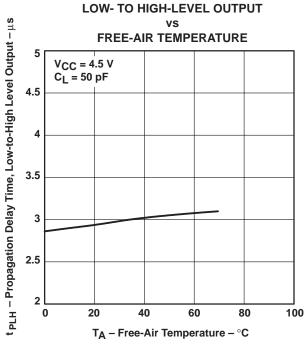
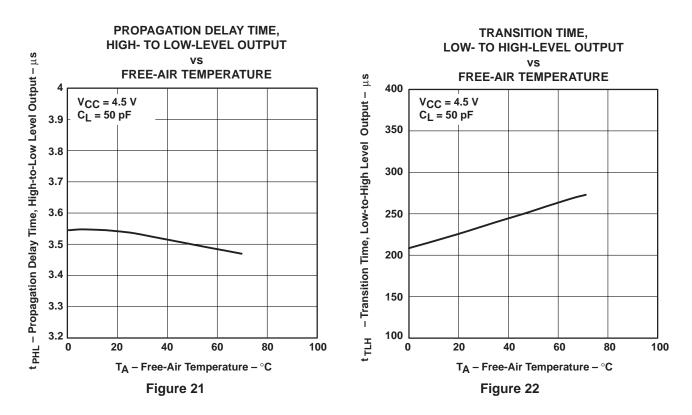


Figure 20



TRANSITION TIME, HIGH- TO LOW-LEVEL OUTPUT

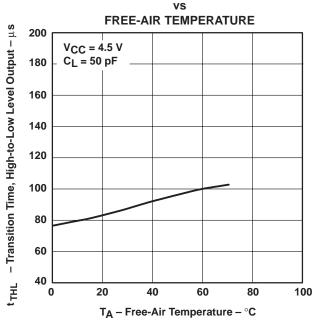


Figure 23

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN75C189AD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75C189A	Samples
SN75C189ADBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	CA189A	Samples
SN75C189ADBRE4	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	CA189A	Samples
SN75C189ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75C189A	Samples
SN75C189AN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN75C189AN	Samples
SN75C189ANE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN75C189AN	Samples
SN75C189ANSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75C189A	Samples
SN75C189D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75C189	Samples
SN75C189DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75C189	Samples
SN75C189DRE4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75C189	Samples
SN75C189N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN75C189N	Samples
SN75C189NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75C189	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".



PACKAGE OPTION ADDENDUM

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- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jun-2022

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75C189ADBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN75C189ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN75C189ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN75C189ANSR	so	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN75C189DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN75C189NSR	so	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75C189ADBR	SSOP	DB	14	2000	356.0	356.0	35.0
SN75C189ADR	SOIC	D	14	2500	356.0	356.0	35.0
SN75C189ADR	SOIC	D	14	2500	340.5	336.1	32.0
SN75C189ANSR	SO	NS	14	2000	356.0	356.0	35.0
SN75C189DR	SOIC	D	14	2500	356.0	356.0	35.0
SN75C189NSR	SO	NS	14	2000	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jun-2022

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN75C189AD	D	SOIC	14	50	507	8	3940	4.32
SN75C189AD	D	SOIC	14	50	506.6	8	3940	4.32
SN75C189AN	N	PDIP	14	25	506	13.97	11230	4.32
SN75C189ANE4	N	PDIP	14	25	506	13.97	11230	4.32
SN75C189D	D	SOIC	14	50	506.6	8	3940	4.32
SN75C189N	N	PDIP	14	25	506	13.97	11230	4.32

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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